

Lonten N-channel 40V, 80A, 4mΩ Power MOSFET

Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- $40V,80A,R_{DS(on).max}=4m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- ♦ 100% EAS Guaranteed
- Green device available

Applications

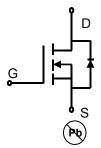
- Motor Drives
- UPS
- ◆ DC-DC Converter

Product Summary

 $\begin{array}{ll} V_{DSS} & 40V \\ R_{DS(on).max} \textcircled{0} \ V_{GS} = 10V & 4.0 m\Omega \\ I_D & 80A \end{array}$

Pin Configuration





N-Channel MOSFET

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	40	V
Continuous drain current (T _C = 25°C) ¹⁾		80	A
Continuous drain current (T _C = 100°C) ¹⁾	I _D	58	A
Pulsed drain current ²⁾	I _{DM}	280	A
Gate-Source voltage	V _{GSS}	±20	V
Avalanche energy ³⁾	E _{AS}	544	mJ
Power Dissipation (T _C = 25°C)	P _D	50	W
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	Rejc	2.5	°C/W

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Package Marking and Ordering Information

Device	Device Package	Marking	
LNN04R040B	DFN5×6	LNN04R040B	

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Static characteristics	<u>'</u>			•		1	
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250uA	40			V	
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.3		2.5	V	
		V _{DS} =40 V, V _{GS} =0 V, T _J = 25°C			1	μΑ	
Drain-source leakage current	I _{DSS}	V _{DS} =40 V, V _{GS} =0 V, T _J = 125°C			5	μA	
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20 V, V _{DS} =0 V			100	nA	
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20 V, V _{DS} =0 V			-100	nA	
Due in course on state resistance	В	V _{GS} =10 V, I _D =20 A		3.1	4	mΩ	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =4.5 V, I _D =10 A		3.9	6.0	mΩ	
Forward transconductance	g fs	V _{DS} =5 V , I _D =50A	26			S	
Dynamic characteristics				•		1	
Input capacitance	Ciss	V 00 V V 0 V		7810		pF	
Output capacitance	Coss	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V},$		677			
Reverse transfer capacitance	Crss	- F = 1MHz		370			
Turn-on delay time	t _{d(on)}			15		- ns	
Rise time	t _r	\ - 20\\\\ -10\\\ -20 A		17			
Turn-off delay time	t _{d(off)}	$-V_{DD} = 20V, V_{GS} = 10V, I_D = 20 A$		52			
Fall time	tf			23			
Gate resistance	Rg	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.12		Ω	
Gate charge characteristics				•		1	
Gate to source charge	Q _{gs}	V 00 V 1 40A		36.4			
Gate to drain charge	Q _{gd}	V _{DS} =20 V, I _D =40A,		37.3		nC	
Gate charge total	Qg	- V _{GS} = 10 V		139		1	
Drain-Source diode characteris	tics and Maxi	mum Ratings		•		•	
Continuous Source Current	Is				80	Α	
Pulsed Source Current ⁴⁾	I _{SM}				280	А	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =40A, T _J =25℃			1.2	V	
Reverse Recovery Time	t _{rr}	I _S =40A, di/dt=100A/us,		42		ns	
Reverse Recovery Charge	Qm	T _J =25℃		120		nC	

Notes:

- 1: The maximum junction current rating is package limited.
- 2: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3: V_{DD} =20V, V_{GS} =10V, L=1mH, I_{AS} =33A, R_G =25 Ω , Starting T_J =25 $^{\circ}$ C.
- 4: Pulse Test: Pulse Width $\leq 300 \, \mu \, \text{s}$, Duty Cycle $\leq 2\%$.

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Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

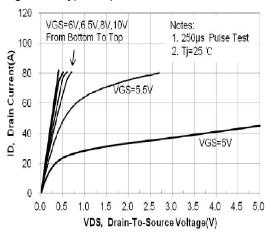


Figure 3. Capacitance Characteristics

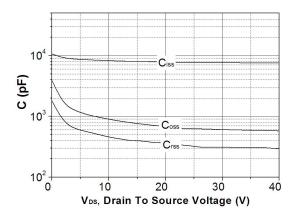


Figure 5. Body-Diode Characteristics

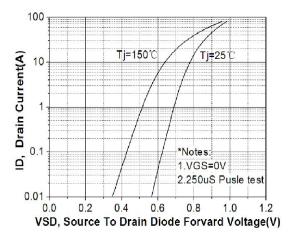


Figure 2. Transfer Characteristics

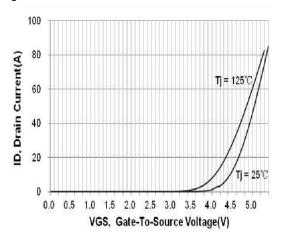


Figure 4. Gate Charge Waveform

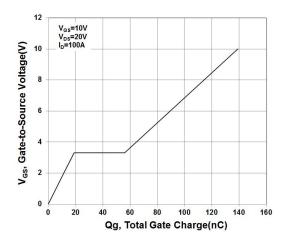
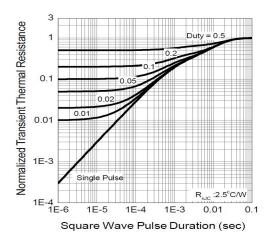


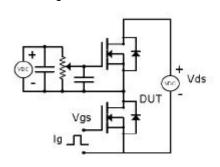
Figure 6. Thermal Transient Impedance





Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform



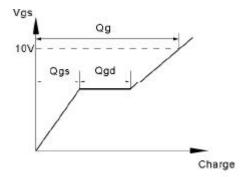
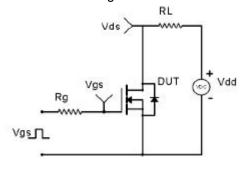


Figure 9. Resistive Switching Test Circuit & Waveforms



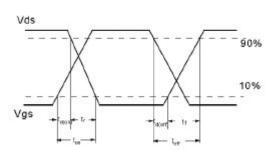
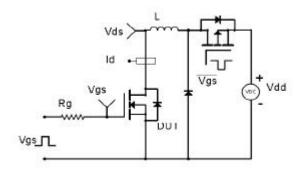


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



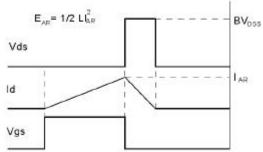
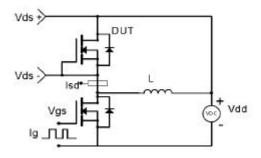
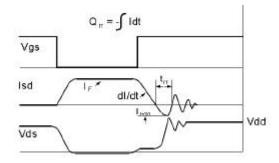


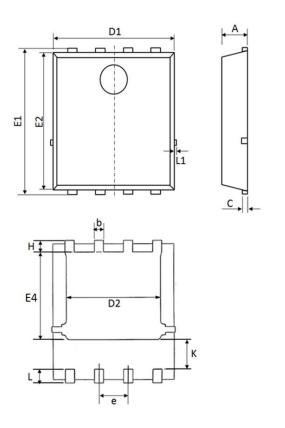
Figure 11. Diode Recovery Circuit & Waveform





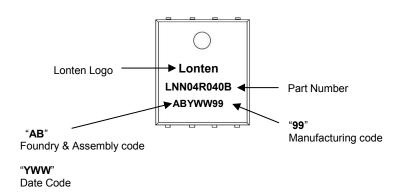


Mechanical Dimensions for DFN5×6



COMMON DIMENSIONS						
SYMBOL	MILLIMETERS			INCHS		
	MIN	NOM	MAX	MIN	NOM	MAX
А	1	1.1	1.2	0.039	0.043	0.047
b	0.3	0.4	0.5	0.012	0.016	0.020
С	0.154	0.254	0.354	0.006	0.010	0.014
D1	5	5.2	5.4	0.197	0.205	0.213
D2	3.8	4.1	4.25	0.150	0.161	0.167
E1	5.95	6.15	6.35	0.234	0.242	0.250
E2	5.66	5.86	6.06	0.223	0.231	0.239
E4	3.52	3.72	3.92	0.139	0.146	0.154
е	1.27 BSC			0.050 BSC		
Н	0.4	0.5	0.6	0.016	0.020	0.024
L	0.5	0.6	0.7	0.020	0.024	0.028
L1	-	-	0.12	-	-	0.005
К	1.14	1.29	1.44	0.045	0.051	0.057

DFN5×6 Part Marking Information





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